

MATERIAL DECLARATION SHEET



Material Number	CD0603 Series			
Product Line	Integrated Passive & Active Devices			
Compliance Date	13-July-2008			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FR-5 BOARD	Substrate/ Terminal	1.357	Copper	7440-50-8	29.34	12.16	41.45
				Nickel	7440-02-0	4.762	1.97	
				Gold	7440-57-5	0.155	0.064	
				Lead	7439-92-1	0.002	0.0008	
				Epoxy resin	-----	65.74	27.249	
2	Wafer	Diode	0.029	Silicon	7440-21-3	94.21	0.838	0.89
				Aluminum	7429-90-5	0.44	0.0039	
				Titanium	7440-32-6	0.08	0.0007	
				Gold	7440-57-5	5.20	0.046	
				Arsenic	7440-38-2	0.07	0.0006	
3	Al Wire	Conductor	0.001	Aluminum	7429-90-5	>.99	>0.0297	0.03
				Silicon	7440-21-3	<1	<0.0003	
4	Silver paste	Welding	0.006	Silver	7440-22-4	75-82	0.135-0.147	0.18
				Phenol Novolac Epoxy	9003-36-5	18-25	0.0324-0.045	
				Dicyanodiamide	461-58-5			
5	Molding Compound	Outer	1.881	Silica fused	60676-86-0	75-95	43.08-54.57	57.45
				Epoxy resin	-----	6-10	3.447-5.745	
				Phenol resin	-----	2-6	1.149-3.447	
				Antimony Trioxide	1309-64-4	0.5-2.5	0.287-1.436	

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				Brominated Epoxy resin	68541-56-0	0.5~2.5	0.287~1.436	
				Carbon Black	1333-86-4	0.1~0.5	0.057~0.287	
		Total weight	3.274					

This Document was updated on: 13-July-2008

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.